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#### MAX3293-MAX3295

## 20Mbps, +3.3V, SOT23 RS-485/ RS-422 Transmitters

### **General Description**

The MAX3293/MAX3294/MAX3295 low-power, high-speed transmitters for RS-485/RS-422 communication operate from a single +3.3V power supply. These devices contain one differential transmitter. The MAX3295 transmitter operates at data rates up to 20Mbps, with an output skew of less than 5ns, and a guaranteed driver propagation delay below 25ns. The MAX3293 (250kbps) and MAX3294 (2.5Mbps) are slew-rate limited to minimize EMI and reduce reflections caused by improperly terminated cables.

The MAX3293/MAX3294/MAX3295 output level is guaranteed at +1.5V with a standard  $54\Omega$  load, compliant with RS-485 specifications. The transmitter draws 5mA of supply current when unloaded, and 1µA in low-power shutdown mode (DE = GND).

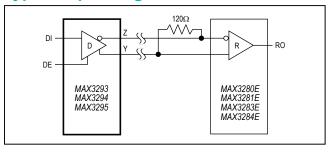
Hot-swap circuitry eliminates false transitions on the data cable during circuit initialization or connection to a live backplane, and short-circuit current limiting and thermal-shutdown circuitry protect the driver against excessive power dissipation.

The MAX3293/MAX3294/MAX3295 are offered in a 6-pin SOT23 package, and are specified over the automotive temperature range.

## **Applications**

- RS-485/RS-422 Communications
- Clock Distribution
- Telecom Equipment
- Automotive
- Security Equipment
- Point-of-Sale Equipment
- Industrial Control

## **Typical Operating Circuit**



#### **Features**

- Space-Saving 6-Pin SOT23 Package
- 250kbps/2.5Mbps/20Mbps Data Rates Available
- Operate from a Single +3.3V Supply
- ESD Protection
   ±9kV–Human Body Model
- Slew-Rate Limited for Errorless Data Transmission (MAX3293/MAX3294)
- 1µA Low-Current Shutdown Mode
- -7V to +12V Common-Mode Input Voltage Range
- Current Limiting and Thermal Shutdown for Driver-Overload Protection
- Hot-Swap Inputs for Telecom Applications
- Automotive Temperature Range (-40°C to +125°C)

#### **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX3293AUT+T	-40°C to +125°C	6 SOT23-6
MAX3294AUT+T	-40°C to +125°C	6 SOT23-6
MAX3295AUT+T	-40°C to +125°C	6 SOT23-6
MAX3295AUT/V+T	-40°C to +125°C	6 SOT23-6

+Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

/V denotes automotive-qualified package.

#### **Selector Guide**

PART	MAXIMUM DATA RATE (Mbps)	SLEW- RATE LIMITED	TOP MARK	
MAX3293AUT+T	0.25	Yes	ABNI or ABVH	
MAX3294AUT+T	2.5	Yes	ABNJ or ABVI	
MAX3295AUT+T	20	No	ABNK or ABVJ	
MAX3295AUT/V+T	20	No	+ACSB	

Pin Configuration appears at end of data sheet.



## 20Mbps, +3.3V, SOT23 RS-485/ RS-422 Transmitters

## **Absolute Maximum Ratings**

(All voltages referenced to GND, unless otherwise noted.)	Operating Temperature Ranges
Supply Voltage (V <sub>CC</sub> )+6V	MAX32AUT40°C to +125°C
DE, DI0.3V to +6V	Storage Temperature Range65°C to +160°C
Y, Z7V to +12.5V	Junction Temperature+160°C
Maximum Continuous Power Dissipation (T <sub>A</sub> = +70°C)	Lead Temperature (soldering, 10s)+300°C
SOT23 (derate 8.2mW/°C above +70°C)654.1mW	Soldering Temperature (reflow)+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **Electrical Characteristics**

 $(V_{CC} = +3.3V \pm 5\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V_{CC} = +3.3V \text{ and } T_A = +25^{\circ}C.) \text{ (Notes 1, 2)}$ 

PARAMETER	SYMBOL	CONI	DITIONS	MIN	TYP	MAX	UNITS	
POWER SUPPLY								
Supply Voltage	V <sub>CC</sub>			3.135	3.300	3.465	V	
Supply Current in Normal Operation	IQ	No load, DI = V <sub>CC</sub> or	No load, DI = $V_{CC}$ or GND, DE = $V_{CC}$			5	mA	
Supply Current in Shutdown Mode	I <sub>SHDN</sub>	No load, DE = GND			1	10	μA	
DRIVER								
Differential Driver Output	\/	Figure 1, DE = V <sub>CC</sub> ,	R = $50\Omega$ (RS-422), T <sub>A</sub> ≤ +85°C	2.0		V <sub>CC</sub>		
Differential Driver Output	V <sub>OD</sub>	DI = GND or V <sub>CC</sub>	R = 27Ω (RS-485), $T_A \le +85^{\circ}C$	1.5		V <sub>CC</sub>	- V	
Change in Magnitude of Differential Output Voltage	$\Delta_{VOD}$	Figure 1, R = $27\Omega$ or $50\Omega$ , DE = $V_{CC}$ (Note 3)				0.2	V	
Driver Common-Mode Output Voltage	V <sub>OC</sub>	Figure 1, R = $27\Omega$ or $50\Omega$ , DE = $V_{CC}$ , DI = $V_{CC}$ or GND		-1		+3	V	
Change in Magnitude of Common-Mode Voltage	ΔV <sub>OC</sub>	Figure 1, R = $27\Omega$ or $50\Omega$ (Note 3)				0.2	V	
DRIVER LOGIC								
Input High Voltage	V <sub>IH</sub>	DE, DI		2.0			V	
Input Low Voltage	V <sub>IL</sub>	DE, DI				0.8	V	
Input Current	I <sub>IN</sub>	DE, DI		-2		+2	μA	
Output Leakage	l.	Y, Z DE = GND,	V <sub>IN</sub> = +12V	-20		+20	- μΑ	
Output Leakage	l <sub>o</sub>	V <sub>CC</sub> = GND or +3.3V	V <sub>IN</sub> = -7V	-20		+20	μΛ	
Driver Short-Circuit Foldback		$(V_{CC} - 1V) \le V_{OUT} \le$	+12V, output high	+25			mA	
Output Current	losfd	-7V ≤ V <sub>OUT</sub> ≤ 1V, output high				-25	IIIA	
Driver Short-Circuit	loop	0 ≤ V <sub>OUT</sub> ≤ +12V, output low		-250			mA	
Output Current	losd	$-7V \le V_{OUT} \le V_{CC}$ , output high				+250	111/4	
Thermal-Shutdown Threshold	T <sub>TS</sub>				160		°C	
Thermal-Shutdown Hysteresis	T <sub>TSH</sub>				40		°C	
ESD Protection		Y, Z	Human Body Model		±9		kV	

## **Switching Characteristics (MAX3293)**

 $(V_{CC} = +3.3V \pm 5\%, T_A = +25^{\circ}C, unless otherwise noted.$  Typical values are at  $V_{CC} = +3.3V.)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Driver Propagation Delay	t <sub>PLH</sub>	Figures 2, 3; $R_{DIFF} = 54\Omega$ ,	400		1300	ns
Driver Propagation Delay	t <sub>PHL</sub>	C <sub>L</sub> = 50pF	400		1300	115
Driver Differential Output Rise	t <sub>R</sub>	Figures 2, 3; $R_{DIFF}$ = 54 $\Omega$ ,	400		1200	ns
or Fall Time	t <sub>F</sub>	C <sub>L</sub> = 50pF	400		1200	115
Driver-Output Skew	tskew	Figures 2, 3; $R_{DIFF}$ = 54 $\Omega$ , $C_L$ = 50pF, t <sub>SKEW</sub> =   t <sub>PLH</sub> - t <sub>PHL</sub>   (Note 5)	-400		+400	ns
Differential Driver-Output Skew	t <sub>DSKEW</sub>	Figures 2, 3; $R_{DIFF}$ = 54 $\Omega$ , $C_L$ = 50pF	-100		+100	ns
Maximum Data Rate		Figures 2, 3; $R_{DIFF}$ = 54 $\Omega$ , $C_L$ = 50pF	250			kbps
Driver Enable to Output High	t <sub>ZH</sub>	Figures 4, 5; S2 closed, $R_L = 500\Omega$ , $C_L = 100pF$			2000	ns
Driver Enable to Output Low	t <sub>ZL</sub>	Figures 4, 5; S1 closed, $R_L = 500\Omega$ , $C_L = 100pF$			2000	ns
Driver Disable Time from Low	t <sub>LZ</sub>	Figures 4, 5; S1 closed, $R_L$ = 500 $\Omega$ , $C_L$ = 100pF			1000	ns
Driver Disable Time from High	t <sub>HZ</sub>	Figures 4, 5; S2 closed, $R_L$ = 500 $\Omega$ , $C_L$ = 100pF			1000	ns
Device-to-Device Propagation Delay Matching		Same power supply, maximum temperature difference between devices = +30°C (Note 5)			900	ns

## **Switching Characteristics (MAX3294)**

( $V_{CC}$  = +3.3V ±5%,  $T_A$  = +25°C, unless otherwise noted. Typical values are at  $V_{CC}$  = +3.3V.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Driver Prepagation Delay	t <sub>PLH</sub>	Figures 2, 3; $R_{DIFF}$ = 54 $\Omega$ ,	24		70	20
Driver Propagation Delay	t <sub>PHL</sub>	C <sub>L</sub> = 50pF	24		70	ns
Driver Differential Output Rise or	t <sub>R</sub>	Figures 2, 3; $R_{DIFF}$ = 54 $\Omega$ ,	10		70	ns
Fall Time	t <sub>F</sub>	C <sub>L</sub> = 50pF	10		70	115
Driver-Output Skew	tskew	Figures 2, 3; $R_{DIFF}$ = 54 $\Omega$ , $C_L$ = 50pF, t <sub>SKEW</sub> =   t <sub>PLH</sub> - t <sub>PHL</sub>   (Note 5)	-40		+40	ns
Differential Driver-Output Skew	t <sub>DSKEW</sub>	Figures 2, 3; $R_{DIFF}$ = 54 $\Omega$ , $C_L$ = 50pF	-6		+6	ns
Maximum Data Rate		Figures 2, 3; $R_{DIFF}$ = 54 $\Omega$ , $C_L$ = 50pF	2.5			Mbps
Driver Enable to Output High t <sub>ZH</sub>		Figures 4, 5; S2 closed, $R_L$ = 500 $\Omega$ , $C_L$ = 100pF			400	ns
Driver Enable to Output Low   tzi   5		Figures 4, 5; S1 closed, $R_L = 500\Omega$ , $C_L = 100pF$			400	ns
I )river I )isable Time from Low   tize		Figures 4, 5; S1 closed, $R_L$ = 500 $\Omega$ , $C_L$ = 100pF			100	ns
Driver Disable Time from High $t_{HZ}$ Figures 4, 5; S2 close $C_L = 100pF$		Figures 4, 5; S2 closed, $R_L$ = 500 $\Omega$ , $C_L$ = 100pF			100	ns
Device-to-Device Propagation Delay Matching		Same power supply, maximum temperature difference between devices = +30°C (Note 5)			46	ns

## **Switching Characteristics (MAX3295)**

 $(V_{CC} = +3.3V \pm 5\%, T_A = +25^{\circ}C, \text{ unless otherwise noted. Typical values are at } V_{CC} = +3.3V.)$ 

PARAMETER	SYMBOL	С	ONDITIONS	MIN	TYP	MAX	UNITS
Driver Propagation Delay	t <sub>PLH</sub>	Figures 2 2: B	Figures 2, 3; $R_{DIFF} = 54\Omega$ , $CL = 50_{pF}$			25	ns
Driver Propagation Delay	t <sub>PHL</sub>	rigules 2, 3, RDIF	F - 5452, GL - 50pF			25	115
	4_		$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$			18.5	
Driver Differential Output Rise	t <sub>R</sub>	Figures 2, 3;	T <sub>A</sub> < +85°C			15	no
or Fall Time		$R_{DIFF} = 54\Omega$ , $C_{I} = 50pF$	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$			18.5	ns
	t <sub>F</sub>	OL COPI	T <sub>A</sub> < +85°C			15	
Driver-Output Skew	tskew	Figures 2, 3; R <sub>DIF</sub> t <sub>SKEW</sub> =   t <sub>PLH</sub> - t <sub>F</sub>	$_{\rm F}$ = 54Ω, C <sub>L</sub> = 50pF,		5		ns
Differential Driver-Output Skew	t <sub>DSKEW</sub>	Figures 2, 3; $R_{DIFF} = 54\Omega$ , $C_L = 50pF$			5		ns
Maximum Data Rate		Figures 2, 3; $R_{DIFF}$ = 54 $\Omega$ , $C_L$ = 50pF, $T_A \le +85^{\circ}C$		20			Mbps
		Figures 2, 3; R <sub>DIFF</sub> = 54Ω, C <sub>L</sub> = 50pF		16			
Driver Enable to Output High	t <sub>ZH</sub>	Figures 4, 5; S2 closed, $R_L = 500\Omega$ , $C_L = 100pF$				400	ns
Driver Enable to Output Low	t <sub>ZL</sub>	Figures 4, 5; S1 cl C <sub>L</sub> = 100pF	Figures 4, 5; S1 closed, $R_L = 500\Omega$ , $C_1 = 100pF$			400	ns
Driver Disable Time from Low	t <sub>LZ</sub>	Figures 4, 5; S1 closed, $R_L = 500\Omega$ , $C_L = 100pF$				100	ns
Driver Disable Time from High	t <sub>HZ</sub>	Figures 4, 5; S2 closed, $R_L$ = 500 $\Omega$ , $C_L$ = 100pF				100	ns
Device-to-Device Propagation Delay Matching		Same power supply, maximum temperature difference between devices = +30°C (Note 5)				25	ns

Note 1: Devices production tested at +25°C. Limits over the operating temperature range are guaranteed by design.

Note 2: All currents into the device are positive; all currents out of the device are negative. All voltages are referenced to device ground, unless otherwise noted.

Note 3:  $\Delta V_{OD}$  and  $\Delta V_{OC}$  are the changes in  $V_{OD}$  and  $V_{OC}$ , respectively, when the DI input changes state. Note 4: The maximum current applies to peak current just prior to foldback current limiting.

Note 5: Guaranteed by design; not production tested.

## **Test Circuits and Timing Diagrams**

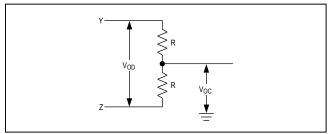


Figure 1. Driver DC Test Load

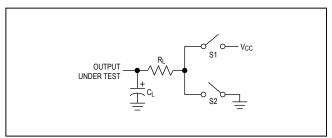


Figure 4. Enable/Disable Timing Test Load

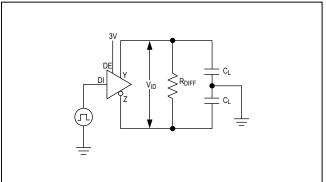


Figure 2. Driver Timing Test Circuit

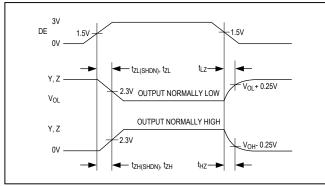


Figure 5. Driver Enable and Disable Times

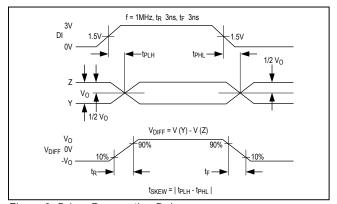
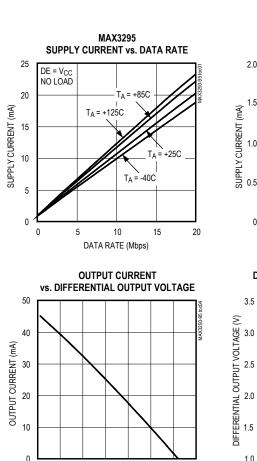
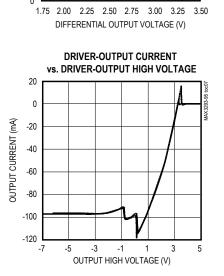
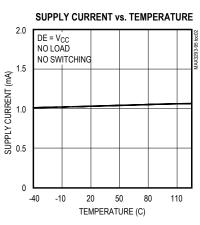


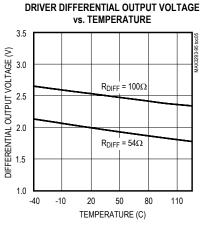
Figure 3. Driver Propagation Delays

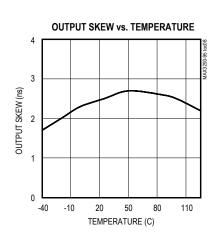
# **Typical Operating Characteristics** (V<sub>CC</sub> = +3.3V, T<sub>A</sub> = +25°C, unless otherwise noted.)

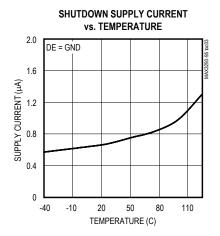


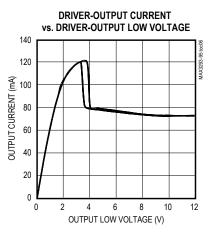


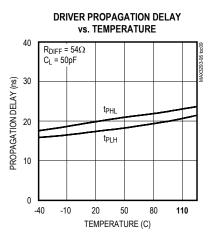




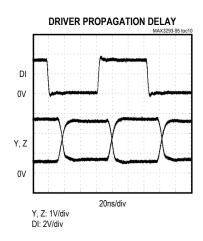


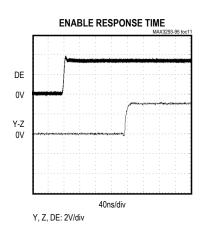


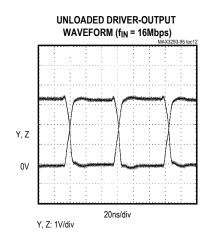


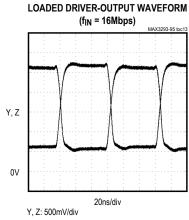


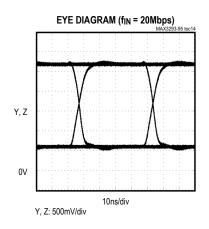
# Typical Operating Characteristics (continued) $(V_{CC} = +3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$











## **Pin Description**

PIN	NAME	FUNCTION
1	DI	Driver Input. A logic low on DI forces the noninverting output (Y) low and the inverting output (Z) high. A logic high on DI forces the noninverting output (Y) high and the inverting output (Z) low.
2	V <sub>CC</sub>	Positive Supply. $V_{CC}$ = +3.3V ±5%. Bypass $V_{CC}$ to GND with a 0.1µF capacitor.
3	DE	Driver Output Enable. Force DE high to enable driver. Pull DE low to disable the driver. Hot-swap input, see the <i>Hot-Swap Capability</i> section.
4	Z	Inverting RS-485/RS-422 Output
5	GND	Ground
6	Υ	Noninverting RS-485/RS-422 Output

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#### **Detailed Description**

The MAX3293/MAX3294/MAX3295 are low-power transmitters for RS-485/RS-422 communication. The MAX3295 operates at data rates up to 20Mbps, the MAX3294 up to 2.5Mbps (slew-rate limited), and the MAX3293 up to 250kbps (slew-rate limited). These devices are enabled using an active-high driver enable (DE) input. When disabled, outputs enter a high-impedance state, and the supply current reduces to 1µA.

The MAX3293/MAX3294/MAX3295 have a hot-swap input structure that prevents disturbance on the differential signal lines when a circuit board is plugged into a "hot" backplane (see the Hot-Swap Capability section). Drivers are also short-circuit current limited and are protected against excessive power dissipation by thermal-shutdown circuitry.

#### **Driver**

The driver accepts a single-ended, logic-level input (DI) and translates it to a differential RS-485/RS-422 level output (Y and Z). Driving DE high enables the driver, while pulling DE low places the driver outputs (Y and Z) into a high-impedance state (see Table 1).

#### Low-Power Shutdown

Force DE low to disable the MAX3293/MAX3294/ MAX3295. In shutdown mode, the device consumes a maximum of 10µA of supply current.

#### **Hot-Swap Capability**

#### **Hot-Swap Input**

When circuit boards are inserted into a "hot" or powered backplane, disturbances to the enable can lead to data errors. Upon initial circuit board insertion, the processor undergoes its power-up sequence. During this period, the output drivers are high impedance and are unable to drive the DE input of the MAX3293/ MAX3294/MAX3295 to a defined logic level. Leakage currents up to 10µA from the high-impedance output could cause DE to drift to an incorrect logic state. Additionally, parasitic circuit board capacitance could

Table 1. MAX3293/MAX3294/ MAX3295 (RS-485/RS-422) Transmitting **Function Table** 

INP	UTS	OUTPUTS		
DE	DI	DI Y		
0	X	Shutdown	Shutdown	
1	0	0	1	
1	1	1	0	

X = Don't care.

cause coupling of V<sub>CC</sub> or GND to DE. These factors could improperly enable the driver.

The MAX3293/MAX3294/MAX3295 eliminate all above issues with hot-swap circuitry. When V<sub>CC</sub> rises, an internal pulldown circuit holds DE low for approximately 10µs. After the initial power-up sequence, the pulldown circuit becomes transparent, resetting the hot-swap tolerable input.

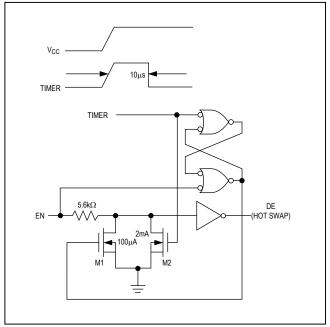


Figure 6. Simplified Structure of the Driver Enable Input (DE)

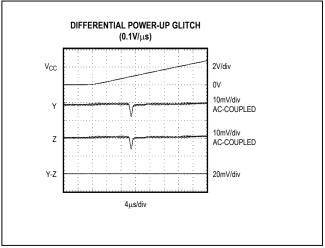


Figure 7. Differential Power-Up Glitch (0.1V/µs)

#### **Hot-Swap Input Circuitry**

The MAX3293/MAX3294/MAX3295 enable input features hot-swap capability. At the input, there are two NMOS devices, M1 and M2 (Figure 6). When  $V_{CC}$  ramps from zero, an internal 10 $\mu$ s timer turns on M2 and sets the SR latch, which also turns on M1. Transistors M2, a 2mA current sink, and M1, a 100 $\mu$ A current sink, pull DE to GND through a 5.6k $\Omega$  resistor. M2 is designed to pull DE to the disabled state against an external parasitic capacitance up to 100pF that may drive DE high. After 10 $\mu$ s, the timer deactivates M2 while M1 remains on, holding DE low against three-state leakages that can drive DE high. M1 remains on until an external source overcomes the required input current. At this time, the SR latch resets and M1 turns

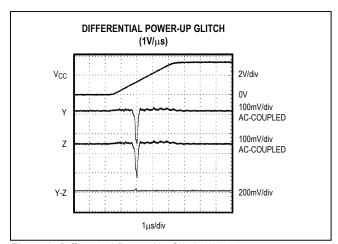


Figure 8. Differential Power-Up Glitch (1V/µs)

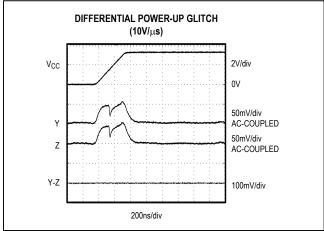


Figure 9. Differential Power-Up Glitch (10V/µs)

off. When M1 turns off, DE reverts to a standard, high-impedance CMOS input. Whenever  $V_{CC}$  drops below 1V, the hot-swap input is reset.

#### **Hot-Swap Line Transient**

During a hot-swap event when the driver is connected to the line and is powered up, the driver must not cause the differential signal to drop below 200mV. Figures 7, 8, and 9 show the results of the MAX3295 during power-up for three different  $V_{CC}$  ramp rates (0.1V/ $\mu$ s, 1V/ $\mu$ s, and 10V/ $\mu$ s). The photos show the  $V_{CC}$  ramp, the single-ended signal on each side of the 100 $\Omega$  termination, as well as the differential signal across the termination.

#### **ESD Protection**

#### **Human Body Model**

Figure 10 shows the Human Body Model, and Figure 11 shows the current waveform it generates when discharged into low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the device through a  $1.5 \mathrm{k}\Omega$  resistor.

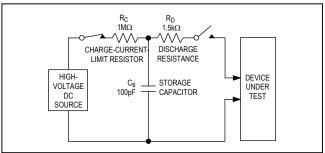


Figure 10. Human Body ESD Test

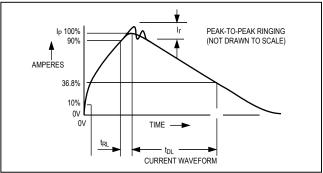


Figure 11. Current Waveform

## Reduced EMI and Reflections (MAX3293/MAX3294)

The MAX3293/MAX3294 are slew-rate limited, minimizing EMI and reducing reflections caused by improperly terminated cables. Figure 12 shows Fourier analysis of the MAX3295 transmitting a 125kHz signal. High-frequency harmonics with large amplitudes are evident. Figure 13 shows the same information, but for the slew-rate-limited MAX3293, transmitting the same signal. The high-frequency harmonics have much lower amplitudes, and the potential for EMI is significantly reduced.

To minimize reflections, the line should be terminated at both ends in its characteristic impedance, and stub lengths off the main line should be kept as short as possible. The slew-rate-limited MAX3293 and MAX3294 are more tolerant of imperfect termination.

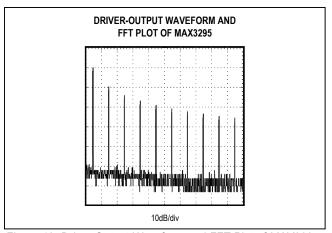
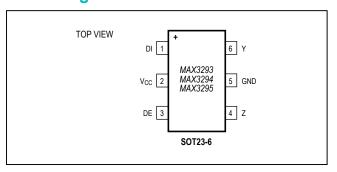


Figure 12. Driver-Output Waveform and FFT Plot of MAX3295 Transmitting a 125kHz Signal

## Pin Configuration



#### **Driver-Output Protection**

Two mechanisms prevent excessive output current and power dissipation caused by faults or by bus contention. The first, a foldback current limit on the output stage, provides immediate protection against short circuits over the whole common-mode voltage range (see the *Typical Operating Characteristics*). The second, a thermal-shut-down circuit, forces the driver outputs into a high-impedance state if the die temperature exceeds +160°C.

### **Chip Information**

PROCESS: BiCMOS

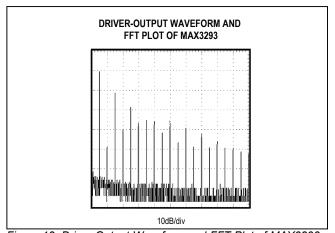


Figure 13. Driver-Output Waveform and FFT Plot of MAX3293 Transmitting a 125kHz Signal

#### Package Information

For the latest package outline information and land patterns (footprints), go to <a href="www.maximintegrated.com/packages">www.maximintegrated.com/packages</a>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE	LAND
TYPE	CODE	NO.	PATTERN NO.
6 SOT23	U6CN+2	21-0058	

#### MAX3293-MAX3295

## 20Mbps, +3.3V, SOT23 RS-485/ **RS-422 Transmitters**

## **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
3	3/11	Added lead-free parts to the Ordering Information and Selector Guide tables	1
4	12/14	Added MAX3295AUT/V+T to Ordering Information	1

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim Integrated's website at www.maximintegrated.com.

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